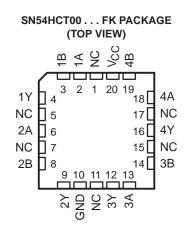
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- Operating Voltage Range of 4.5 V to 5.5 V
- Outputs Can Drive Up To 10 LSTTL Loads
- Low Power Consumption, 20-μA Max I_{CC}

SN54HCT00 ... J OR W PACKAGE SN74HCT00 ... D, DB, N, NS, OR PW PACKAGE (TOP VIEW)

1A [1	Ο	14] v _{cc}
1B [13	4B
1Y [3		12] 4A
2A [4		11] 4Y
2B [5		10] 3B
2Y [6		9] 3A
GND [7		8] 3Y

- Typical t_{pd} = 10 ns
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 μA Max
- Inputs Are TTL-Voltage Compatible



NC - No internal connection

description/ordering information

These devices contain four independent 2-input NAND gates. They perform the Boolean function $Y = \overline{A \bullet B}$ or $Y = \overline{A + B}$ in positive logic.

TA	PACKAGET		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	PDIP – N	Tube of 25	SN74HCT00N	SN74HCT00N	
		Tube of 50	SN74HCT00D		
	SOIC – D	Reel of 2500	SN74HCT00DR	HCT00	
		Reel of 250	SN74HCT00DT	1	
–40°C to 85°C	SOP – NS	Reel of 2000	SN74HCT00NSR	HCT00	
	SSOP – DB	Reel of 2000	SN74HCT00DBR	HT00	
		Tube of 90	SN74HCT00PW		
	TSSOP – PW	Reel of 2000	SN74HCT00PWR	HT00	
		Reel of 250	SN74HCT00PWT		
	CDIP – J	Tube of 25	SNJ54HCT00J	SNJ54HCT00J	
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HCT00W	SNJ54HCT00W	
	LCCC – FK	Tube of 55	SNJ54HCT00FK	SNJ54HCT00FK	

ORDERING INFORMATION

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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FUNCTION TABLE (each gate)					
INP	UTS	OUTPUT			
Α	В	Y			
Н	Н	L			
L	Х	Н			
Х	L	Н			

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{CC}$) (see Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$ Continuous output current, I_O ($V_O = 0$ to V_{CC}) Continuous current through V_{CC} or GND Package thermal impedance, θ_{JA} (see Note 2):	ee Note 1) C) (see Note 1) D package DB package N package NS package	±20 mA ±20 mA ±25 mA ±50 mA 86°C/W 96°C/W 80°C/W 76°C/W
	PW package	
Storage temperature range, T _{stg}		

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			SN	154HCT00	SN	174HCT0	0	UNIT
			MIN	NOM MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.5	5 💉 5.5	4.5	5	5.5	V
VIH	High-level input voltage	V _{CC} = 4.5 V to 5.5 V	2	N	2			V
VIL	Low-level input voltage	V_{CC} = 4.5 V to 5.5 V		0.8			0.8	V
VI	Input voltage		0	Vcc	0		VCC	V
VO	Output voltage		0	S Vcc	0		VCC	V
$\Delta t/\Delta v$	Input transition rise/fall time		C	500			500	ns
Τ _Α	Operating free-air temperature		-55	125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics	over	recommended	operating	free-air	temperature	range	(unless
otherwise noted)					-	•	

PARAMETER	TEST CONDITIONS		Vaa	T _A = 25°C			SN54F	ICT00	SN74H	ICT00	UNIT
PARAMETER	TEST CO	NDITIONS	Vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
Vau	$V_{I} = V_{IH} \text{ or } V_{IL}$	I _{OH} = -20 μA	4.5 V	4.4	4.499		4.4		4.4		V
VOH	VI = VIH OL VIL	I _{OH} = -4 mA	4.5 V	3.98	4.3		3.7		3.84		v
Ve	$\lambda = \lambda = 0$	I _{OL} = 20 μA	4.5 V		0.001	0.1		0,1		0.1	V
VOL	$V_{I} = V_{IH} \text{ or } V_{IL}$	I _{OL} = 4 mA	4.5 V		0.17	0.26		0.4		0.33	v
li li	AI = ACC or 0		5.5 V		±0.1	±100		±1000		±1000	nA
ICC	$V_I = V_{CC} \text{ or } 0,$	I ^O = 0	5.5 V			2	(C)	40		20	μΑ
∆lcc‡	One input at 0.5 V of Other inputs at 0 or		5.5 V		1.4	2.4	Pook	3		2.9	mA
Ci			4.5 V to 5.5 V		3	10	Y	10		10	pF

[†] This is the increase in supply current for each input that is at one of the specified TTL voltage levels, rather than 0 V or V_{CC}.

switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Figure 1)

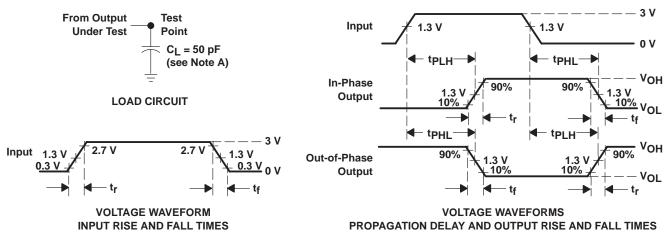
PARAMETER	FROM	то	то		λ = 25°C	;	SN54HCT00	SN74HCT00	UNIT
PARAMETER	(INPUT)	(OUTPUT)	Vcc	MIN	TYP	MAX	MIN MAX	MIN MAX	UNIT
÷.	t _{pd} A or B	Y	4.5 V		11	20	30	25	ns
чра			5.5 V		10	18	27	22	115
* .		V	4.5 V		9	15	22	19	
t		Y Y	5.5 V		8	14	20	17	ns

operating characteristics, T_{A} = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance per gate	No load	20	pF



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PARAMETER MEASUREMENT INFORMATION

- NOTES: A. CL includes probe and test-fixture capacitance.
 - B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_Q = 50 Ω, t_r = 6 ns, t_f = 6 ns.
 - C. The outputs are measured one at a time with one input transition per measurement.
 - D. tPLH and tPHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- \triangle The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012 variation AB.



MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MECHANICAL DATA

MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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